

PATENT ABSTRACTS OF JAPAN

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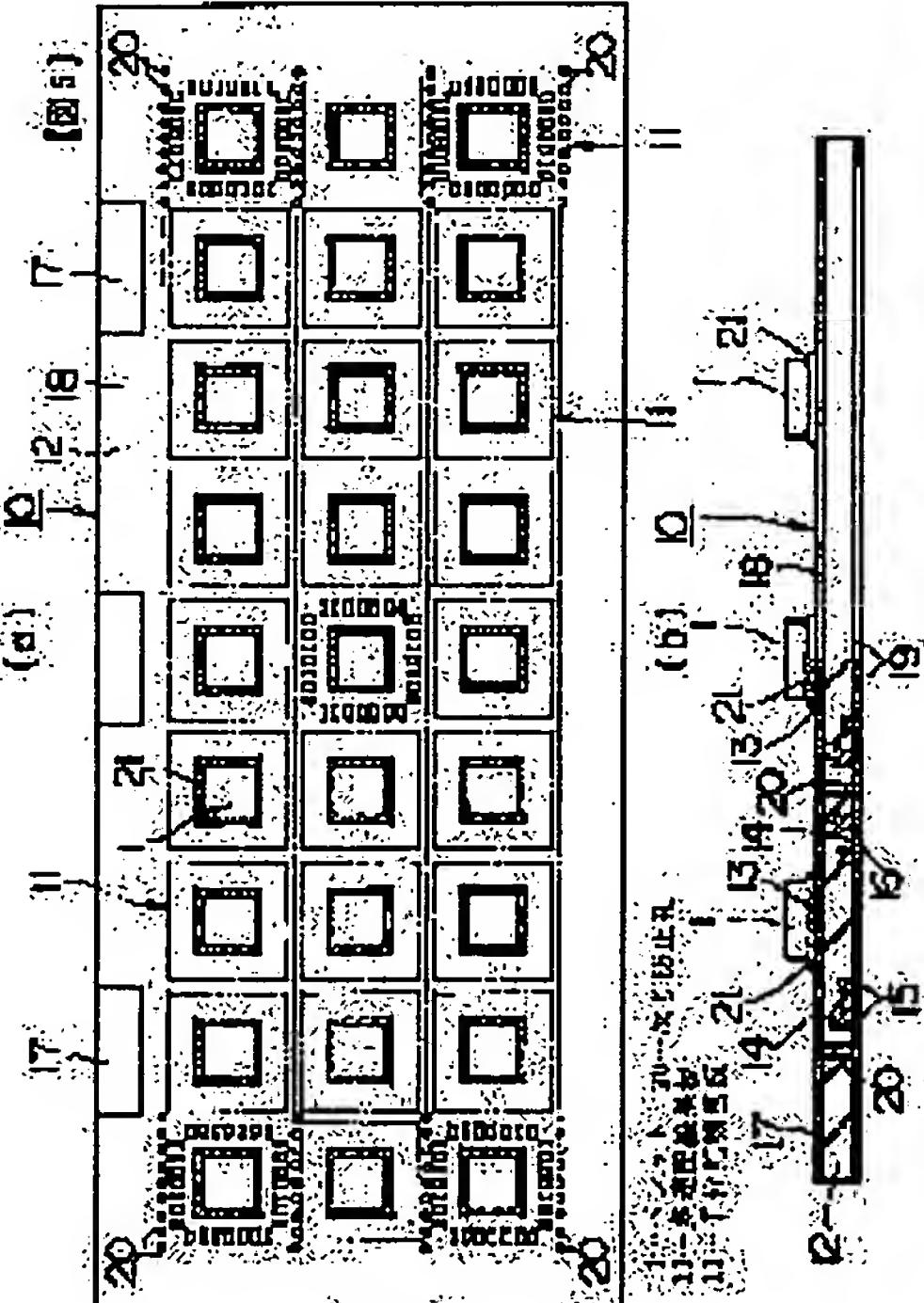
(54) METHOD FOR PRODUCING SEMICONDUCTOR DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To prevent a multiple wiring board for use in MAP from warping.

SOLUTION: After pellets 1 are bonded to a plurality of unit wiring boards 11 of the multiple wiring board 10 and a group of pellets 1 is sealed in batch with a resin-sealing body 23, the multiple wiring board 10 and the resin-sealing body 23 are cut into individual unit wiring boards 11. In this method of producing individual BGA ICs by MAP, a large number of warpage-preventing holes 20 are made along the border line of the unit wiring boards 11 of the multiple wiring board 10.

Since thermal stresses, acting on the multiple wiring board in pellet bonding process, or the like, can be absorbed by the large number of warpage-preventing holes, the multiple wiring board can be prevented from warping. Consequently, splitting or cracking of the multiple wiring board, open circuit or short circuit of the inner terminal, outer terminal and electric wiring of the unit wiring board, underfilling of the resin-sealing body, generation of voids, and the like, can be prevented and the yield, quality and reliability can be enhanced in the method for producing a BGA IC using MAP.



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